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(54) **EXPOSED COPPER AREA FOR PORT
ELECTROSTATIC DISCHARGE
PROTECTION**

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ABSTRACT

The disclosure generally relates to a conductive layer having one or more protrusions configured to attract an electrostatic discharge (“ESD”) arc. The device may be any device, such as a smartphone, tablet, earbuds, etc. The device may include a microphone and, therefore, may include a microphone opening. The conductive layer may include a conductive opening axially aligned with the microphone opening and one or more protrusions extending radially inwards towards the center of the conductive opening.

